

CMOS LDO Regulators for Portable Equipments

1ch 500mA CMOS LDO Regulators

Pb Rol



General Description

BUxxSD5 series are high-performance CMOS LDO regulators with output current ability of up to 500mA.

These devices have excellent noise and load response characteristics despite of its low circuit current consumption of $33\mu A$. They are most appropriate for various applications such as power supplies for logic IC, RF, and camera modules.

Features

- High Output Voltage Accuracy: ±2.0% (In all recommended conditions)
- High Ripple Rejection: 68 dB (Typ, 1 kHz,)
- Compatible with small ceramic capacitor (Cin=Cout=0.47 µF)
- Low Current Consumption: 33 µA
- Output Voltage ON/OFF control
- Built-in Over Current Protection Circuit (OCP)
- Built-in Thermal Shutdown Circuit (TSD)
- Package SSOP5 is similar to SOT23-5(JEDEC)

Key Specifications

■ Input Power Supply Voltage Range: 1.7V to 6.0V
■ Output Current Range: 0 to 500mA
■ Operating Temperature Range: -40°C to +105°C
■ Output Voltage Lineup: 3.3V
■ Output Voltage Accuracy: ±2.0%
■ Circuit Current: 33µA(Typ.)
■ Standby Current: 0µA (Typ.)

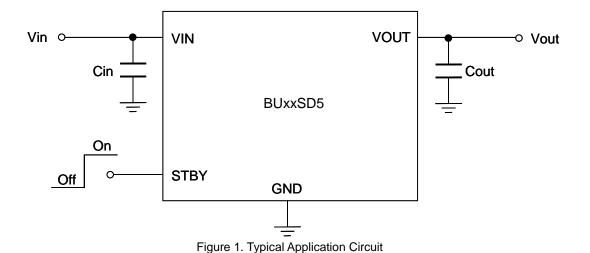
● Package SSOP5 W(Typ.) x D(Typ.) x H(Max.) 2.90mm x 2.80mm x 1.25mm



Applications

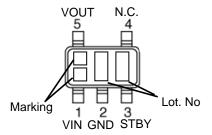
- Portable devices
- Camera modules
- Other electronic devices using microcontrollers or logic circuits

● Typical Application Circuit



OProduct structure : Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays

●Pin Configuration



Pin Description

Pin No.	Symbol	Function		
1	VIN	Input Pin		
2	GND	GND Pin		
3	STBY	Output Control Pin (High:ON, Low:OFF)		
4	N.C.	No Connect		
5	VOUT	Output Pin		

Block Diagram

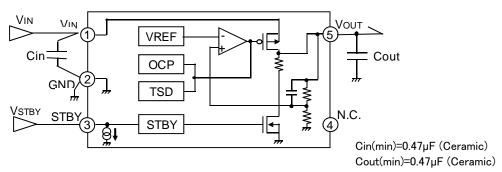


Figure 2. Block diagram

● Absolute Maximum Ratings

Parameter	Symbol Rating		Unit
Maximum Power Supply Voltage Range	VMAX	-0.3 to +6.5	V
Power Dissipation	Pd	540 ^(*1)	mW
Maximum Junction Temperature	Tjmax	+125	°C
Operating Temperature Range	Topr	-40 to +105	°C
Storage Temperature Range	Tstg	-55 to +125	°C

^(*1) Derate by 5.6mW/°C when operating above Ta=25°C.(When mounted on a board 70mm × 70mm × 1.6mm glass-epoxy board, two layer)

Recommended Operating Ratings

Parameter	Symbol	Limit	Unit
Input Power Supply Voltage Range	VIN	1.7 to 6.0	V
Maximum Output Current	Імах	500	mA

Recommended Operating Conditions

Parameter	Symbol	Rating		Unit	Conditions	
		Min.	Тур.	Max.	Offic	Conditions
Input capacitor	Cin	0.47 ^(*2)	1.0	1	μF	A ceramic capacitor is recommended.
Output capacitor	Cout	0.47 ^(*2)	1.0	_	μF	A ceramic capacitor is recommended.

^(*2) Set the value of the capacitor so that it does not fall below the minimum value. Take into consideration the temperature characteristics, DC device characteristics, and degradation with time.

●Electrical Characteristics

(Unless otherwise noted, Ta=-40 to 105°C, VIN=VOUT+1.0 $V^{(*3)}$, VSTBY=1.5V, Cin=1 μ F, Cout=1 μ F.)

PARAMETER		a=-40 to	Limit		المنا ا	O and distance		
		Symbol	MIN.	TYP.	MAX.	Unit	Conditions	
Output Voltage		Vout	Vоит × 0.98	Vout	Vо∪т × 1.02	V	IOUT=1mA, VOUT≧2.5V, VIN=VOUT+0.5 to 6.0V VOUT<2.5V, VIN=3.0 to 6.0V Ta=-40 to +105°C (*4.5.6)	
Line Regulation		VDLI	-	4	10	mV	IOUT=10mA VOUT≦2.5V, VIN=3.0 to 6.0V	
Line Regulation		VDLI		6	15	mV	IOUT=10mA VOUT>2.5V, VIN=VOUT+0.5 to 6.0V	
Load Regulation1		VDLO1	-	0.5	5	mV	IOUT=1 to 100mA	
Load Regulation2		VDLO2	-	2.5	25	mV	IOUT=1 to 500mA	
			-	400	700	mV	1.0V≦VouT<1.2V, IouT=100mA	
			-	280	550	mV	1.2V≦VouT<1.5V, IouT=100mA	
			-	180	370	mV	1.5V≦VouT<1.7V, IouT=100mA	
Dropout Voltage		VDROP	-	150	290	mV	1.7V≦Vouт<2.1V, Iouт=100mA	
			-	110	220	mV	2.1V≦VouT<2.5V, IouT=100mA	
			-	100	180	mV	2.5V≦VouT<2.8V, IouT=100mA	
			-	85	150	mV	2.8V≦Vout, lout=100mA	
Limit Current		ILMAX	-	800	-	mA	Vo=Vout×0.98, Ta=25°C	
Short Current		ISHORT	-	180	-	mA	Vo=0V, Ta=25°C	
Circuit Current		IGND	-	33	80	μΑ	IOUT=0mA	
Circuit Current (STB)	Y)	ICCST	-	-	2.0	μΑ	VSTBY=0V	
Ripple Rejection Rat	io	R.R.	-	68	-	dB	VRR=-20dBv,fRR=1kHz,IOUT=10mA	
Load Transient Response		VLOT	-	±65	-	mV	IOUT=1 to 150mA,Trise=Tfall=1μs, VIN=VOUT+1.0V (*5)	
Output Noise Voltage		Vnois	-	30	-	μVrms	Bandwidth 10 to 100kHz	
Discharge Resistor		RDSC	20	50	80	Ω	VIN=4.0V, VSTBY=0V, VOUT=4.0V, Ta=25°C	
STBY Control	ON	VstbH	1.1	-	Vin	V		
Voltage OFF		VSTBL	-0.2	-	0.5	V	Ta=25°C	
STBY Pin Current	STBY Pin Current		-	-	4.0	μΑ		

^(*3) VIN=3.5V for VOUT < 2.5V.

^(*4) Operating Conditions are limited by Pd.

^(*5) Typical values apply for Ta=25 $^{\circ}$ C.

^(*6) VIN=3.0V to 6.0V for VOUT < 2.5V.

● Reference data BU33SD5WG (Unless otherwise specified, Ta=25°C.)

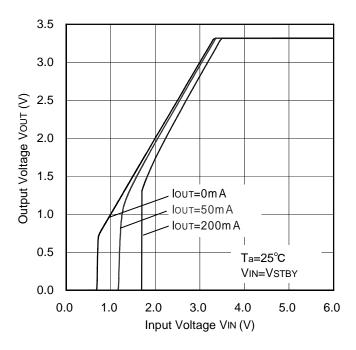


Figure 3. Output Voltage vs. Input Voltage

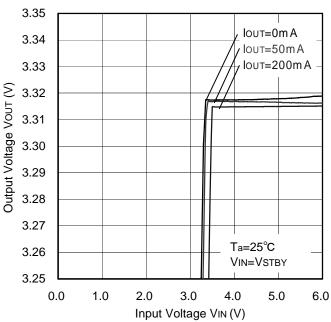


Figure 4. Line Regulation

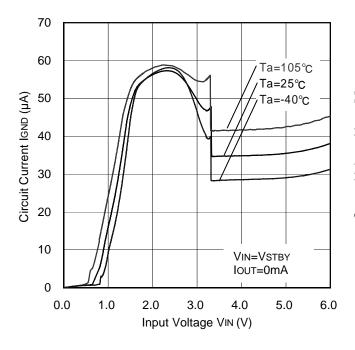


Figure 5. Circuit Current vs. Input Voltage

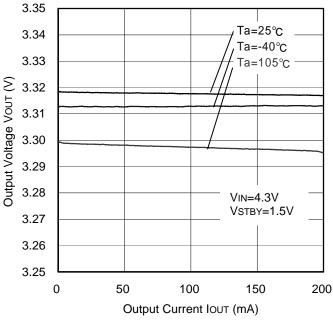


Figure 6. Load Regulation

● Reference data BU33SD5WG (Unless otherwise specified, Ta=25°C.)

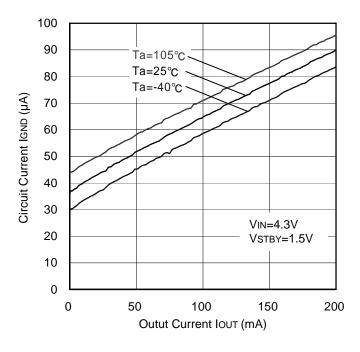


Figure 7. Circuit Current vs. Output Current

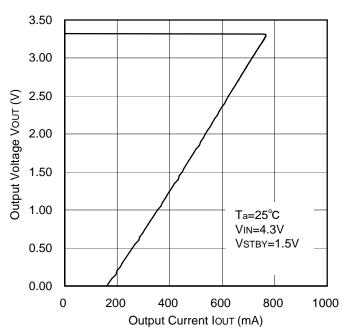


Figure 8. OCP Threshold

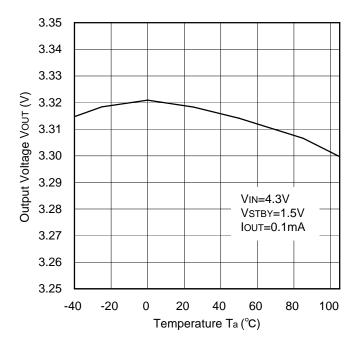


Figure 9. Output Voltage vs. Temperature

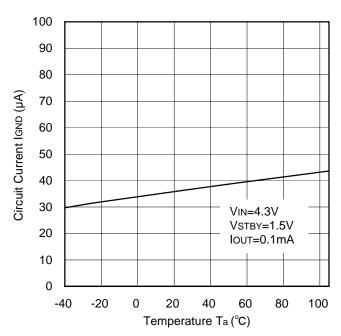


Figure 10. Circuit Current vs. Temperature

● Reference data BU33SD5WG (Unless otherwise specified, Ta=25°C.)

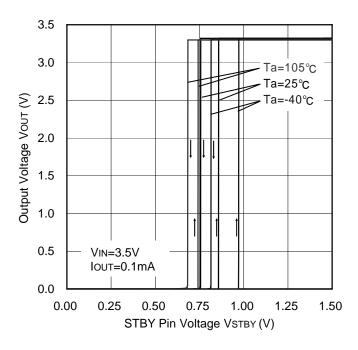


Figure 11. STBY Threshold

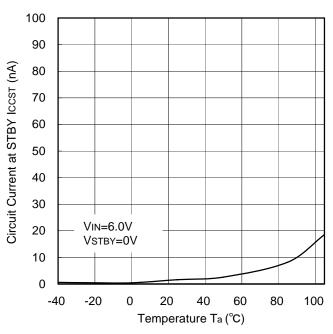


Figure 12. Circuit Current (at STBY) vs. Temperature

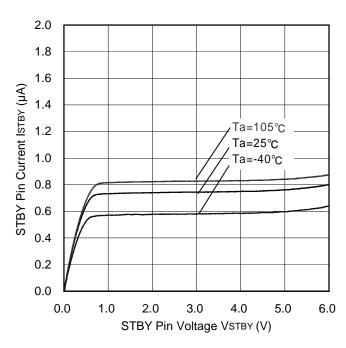


Figure 13. STBY Pin Current vs. STBY Pin Voltage

●Input/Output Capacitor

It is recommended that an input capacitor is placed near pins between the VCC pin and GND as well as an output capacitor between the output pin and GND. The input is valid when the power supply impedance is high or when the PCB trace has significant length. For the output capacitor, the greater the capacitance, the more stable the output will be depending on the load and line voltage variations. However, please check the actual functionality of this capacitor by mounting it on a board for the actual application. Ceramic capacitors usually have different, thermal and equivalent series resistance characteristics, and may degrade gradually over continued use.

For additional details, please check with the manufacturer, and select the best ceramic capacitor for your application

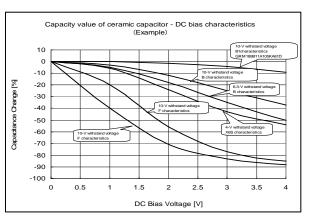


Figure 14. Capacity-bias characteristics

● Equivalent Series Resistance (ESR) of a Ceramic Capacitor

Capacitors generally have ESR (equivalent series resistance) and it operates stably in the ESR-IOUT area shown on the right. Since ceramic capacitors, tantalum capacitors, electrolytic capacitors, etc. generally have different ESR, please check the ESR of the capacitor to be used and use it within the stability area range shown in the right graph for evaluation of the actual application.

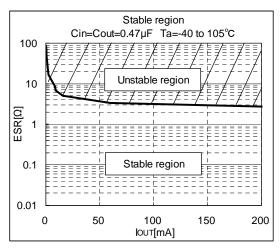


Figure 15. Stability area characteristics (Example)

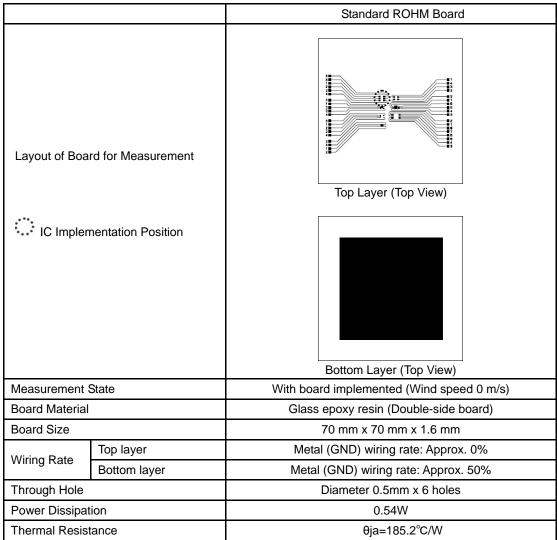
● Power Dissipation (Pd)

As for power dissipation, an estimate of heat reduction characteristics and internal power consumption of IC are shown, so please use these for reference. Since power dissipation changes substantially depending on the implementation conditions (board size, board thickness, metal wiring rate, number of layers and through holes, etc.), it is recommended to measure Pd on a set board. Exceeding the power dissipation of IC may lead to deterioration of the original IC performance, such as causing the operation of the thermal shutdown circuit or reduction in current capability. Therefore, be sure to prepare sufficient margin within power dissipation for usage.

Calculation of the maximum internal power consumption of IC (PMAX)

PMAX=(VIN-Vout)×IoMAX Where: VIN=Input voltage Vout= Output voltage IoMAX: Maximum output current)

OMeasurement conditions



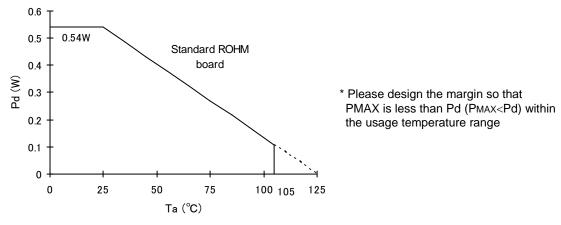


Figure 16. SSOP5 Power dissipation heat reduction characteristics (Reference)

●I/O Equivalence Circuits

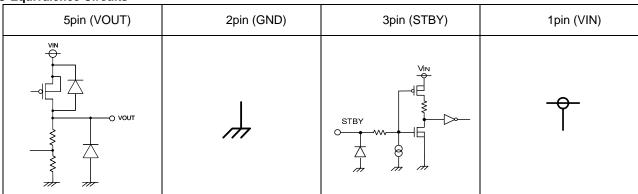


Figure 17. Input / Output equivalent circuit

Operational Notes

1) Absolute maximum ratings

This produced with strict quality control, however it may be destroyed if operated beyond its absolute maximum ratings. In addition, it is impossible to predict all destructive situations such as short-circuit modes, open circuit modes, etc. Therefore, it is important to consider circuit protection measures, like adding a fuse, in case the IC is operated in a special mode exceeding the absolute maximum ratings.

2) GND Potential

GND potential must be the lowest potential of all pins of the IC at all operating conditions. Ensure that no pins are at a voltage below the ground pin at any time, even during transient condition.

3) Setting of Heat

Carry out the heat design that have adequate margin considering Pd of actual working states.

4) Pin Short and Mistake Fitting

When mounting the IC on the PCB, pay attention to the orientation of the IC. If there is mistake in the placement, the IC may be burned up.

5) Actions in Strong Magnetic Field

Using the IC within a strong magnetic field may cause the IC to malfunction.

6) Mutual Impedance

Use short and wide wiring tracks for the power supply and ground to keep the mutual impedance as small as possible. Use a capacitor to keep ripple to a minimum.

7) STBY Pin Voltage

To enable standby mode for all channels, set the STBY pin to 0.5 V or less, and for normal operation, to 1.1 V or more. Setting STBY to a voltage between 0.5 and 1.1 V may cause malfunction and should be avoided. Keep transition time between high and low (or vice versa) to a minimum.

Additionally, if STBY is shorted to VIN, the IC will switch to standby mode and disable the output discharge circuit, causing a temporary voltage to remain on the output pin. If the IC is switched on again while this voltage is present, overshoot may occur on the output. Therefore, in applications where these pins are shorted, the output should always be completely discharged before turning the IC on.

8) Over Current Protection Circuit

Over current and short circuit protection is built-in at the output, and IC destruction is prevented at the time of load short circuit. These protection circuits are effective in the destructive prevention by sudden accidents, please avoid applications to where the over current protection circuit operates continuously.

9) Thermal Shutdown

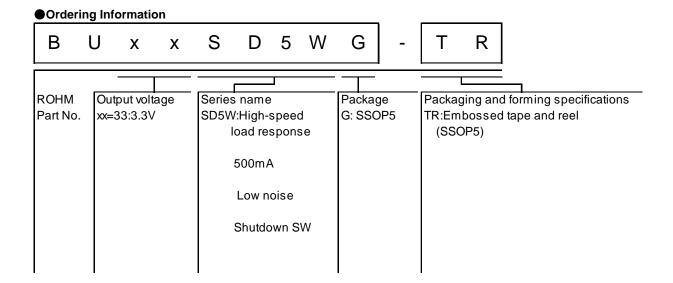
This IC has Thermal Shutdown Circuit (TSD Circuit). When the temperature of IC Chip is higher than 175°C, the output is turned off by TSD Circuit. TSD Circuit is only designed for protecting IC from thermal over load. Therefore it is not recommended that you design application where TSD will work in normal condition.

10) Actions under Strong light

A strong light like a halogen lamp may be caused malfunction. In our testing, fluorescence light and white LED causes little effects for the IC, but infrared light causes strong effects on the IC. The IC should be shielded from light like sunrays or halogen lamps.

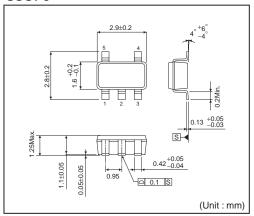
11) Output capacitor

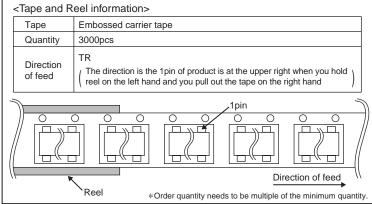
To prevent oscillation at output, it is recommended that the IC be operated at the stable region shown in Figure 15. It operates at the capacitance of more than $0.47\mu F$. As capacitance is larger, stability becomes more stable and characteristic of output load fluctuation is also improved.



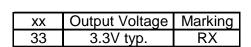
● Physical Dimension Tape and Reel Information

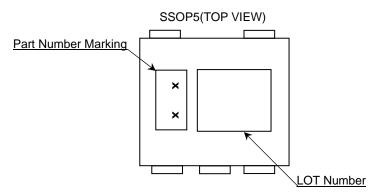
SSOP5





Marking Diagram





Revision History

Date	Revision	Changes			
24.Dec.2013	001	New Release			
24.Mar.2014	002	 Moved the descriptions of Limit current and Short current from P11 to P4. Added the description of Discharge resistor to P4. 			

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CLASSⅢ	CLACCIII	CLASSIIb	CI ACCIII	
CLASSIV	CLASSⅢ	CLASSⅢ	- CLASSⅢ	

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- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
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- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
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